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[ON Semiconductor](#)  
[NSS30071MR6T1G](#)

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# NSS30071MR6T1G

## 30 V, 0.7 A, Low $V_{CE(sat)}$ NPN Transistor

ON Semiconductor's e<sup>2</sup>PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

- This is a Pb-Free Device

### MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	30	V
Collector-Base Voltage	$V_{CBO}$	40	V
Emitter-Base Voltage	$V_{EBO}$	5.0	V
Collector Current	$I_C$	700	mA
Base Current	$I_B$	350	mA
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	$P_D$	342	mW
Total Power Dissipation @ $T_C = 85^\circ\text{C}$	$P_D$	178	mW
Thermal Resistance - Junction-to-Ambient (Note 1)	$R_{\theta JA}$	366	$^\circ\text{C/W}$
Total Power Dissipation @ $T_C = 25^\circ\text{C}$	$P_D$	665	mW
Total Power Dissipation @ $T_C = 85^\circ\text{C}$	$P_D$	346	mW
Thermal Resistance - Junction-to-Ambient (Note 2)	$R_{\theta JA}$	188	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

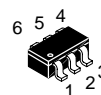
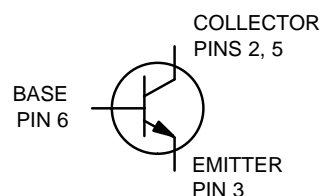
1. Minimum FR-4 or G-10 PCB, Operating to Steady State.
2. Mounted onto a 2" square FR-4 Board (1" sq 2 oz Cu 0.06" thick single sided), Operating to Steady State.



ON Semiconductor®

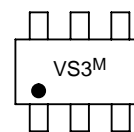
<http://onsemi.com>

**30 VOLTS**  
**0.7 AMPS**  
**NPN LOW  $V_{CE(sat)}$  TRANSISTOR**  
**EQUIVALENT  $R_{DS(on)}$  200 m $\Omega$**



**SC-74**  
**CASE 318F**  
**STYLE 2**

### DEVICE MARKING



VS3 = Specific Device Code  
 M = Date Code

### ORDERING INFORMATION

Device	Package	Shipping†
NSS30071MR6T1G	SC-74 (Pb-Free)	10000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure. BRD8011/D.

## NSS30071MR6T1G

**ELECTRICAL CHARACTERISTICS** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Characteristic	Min	Typ	Max	Unit
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**OFF CHARACTERISTICS**

$V_{(BR)CBO}$	Collector–Base Breakdown Voltage ( $I_C = 100 \mu\text{Adc}$ )	40	–	–	Vdc
$V_{(BR)CEO}$	Collector–Emitter Breakdown Voltage ( $I_C = 10 \text{ mAdc}$ )	30	–	–	Vdc
$V_{(BR)EBO}$	Emitter–Base Breakdown Voltage ( $I_E = 100 \mu\text{Adc}$ )	5.0	–	–	Vdc
$I_{CBO}$	Collector Cutoff Current ( $V_{CB} = 25 \text{ Vdc}$ , $I_E = 0 \text{ Adc}$ ) ( $V_{CB} = 25 \text{ Vdc}$ , $I_E = 0 \text{ Adc}$ , $T_A = 125^\circ\text{C}$ )	–	–	1.0 10	$\mu\text{Adc}$
$I_{EBO}$	Emitter Cutoff Current ( $V_{EB} = 5.0 \text{ Vdc}$ , $I_C = 0 \text{ Adc}$ )	–	–	10	$\mu\text{Adc}$

**ON CHARACTERISTICS**

$h_{FE}$	DC Current Gain ( $V_{CE} = 3.0 \text{ Vdc}$ , $I_C = 100 \text{ mAdc}$ )	150	–	–	Vdc
$V_{CE(sat)}$	Collector–Emitter Saturation Voltage ( $I_C = 500 \text{ mAdc}$ , $I_B = 50 \text{ mAdc}$ )	–	–	0.25	Vdc
$V_{CE(sat)}$	Collector–Emitter Saturation Voltage ( $I_C = 700 \text{ mAdc}$ , $I_B = 70 \text{ mAdc}$ )	–	–	0.4	Vdc
$V_{BE(sat)}$	Base–Emitter Saturation Voltage ( $I_C = 700 \text{ mAdc}$ , $I_B = 70 \text{ mAdc}$ )	–	–	1.1	Vdc
$V_{BE(on)}$	Collector–Emitter Saturation Voltage ( $I_C = 700 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ )	–	–	1.0	Vdc

**NSS30071MR6T1G**

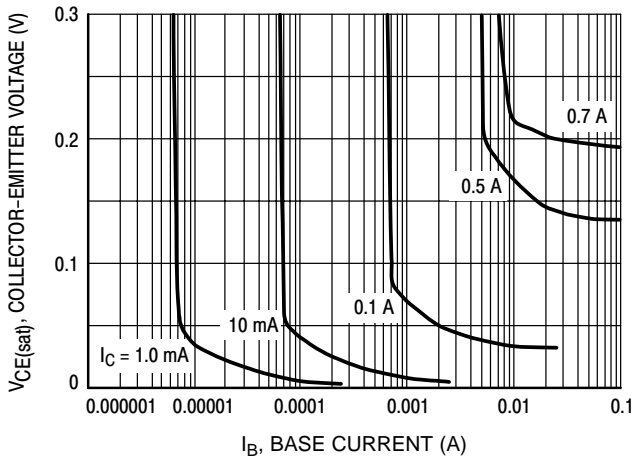


Figure 1. Collector Saturation Region

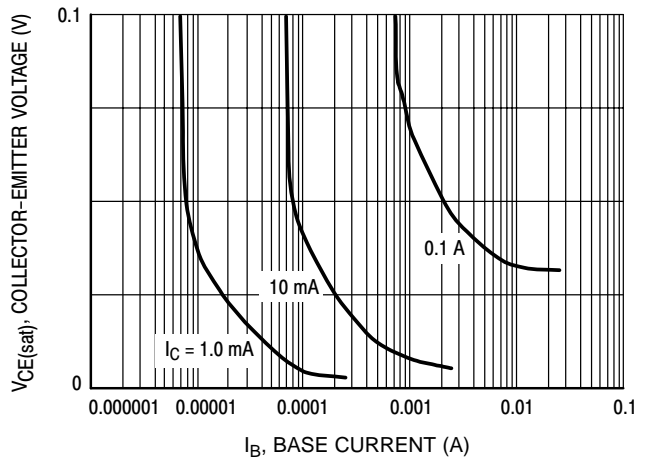


Figure 2. Collector Saturation Region

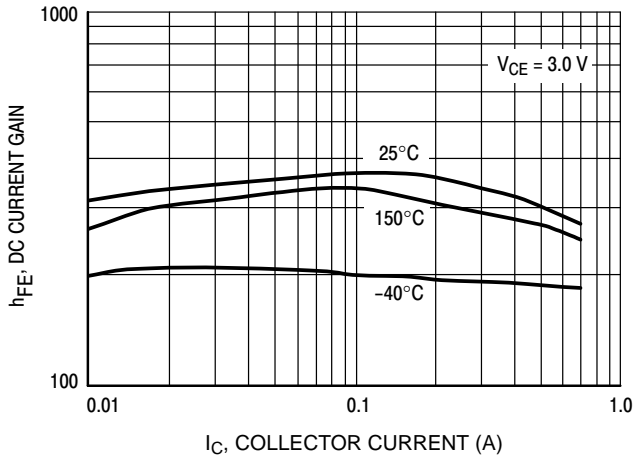


Figure 3. DC Current Gain

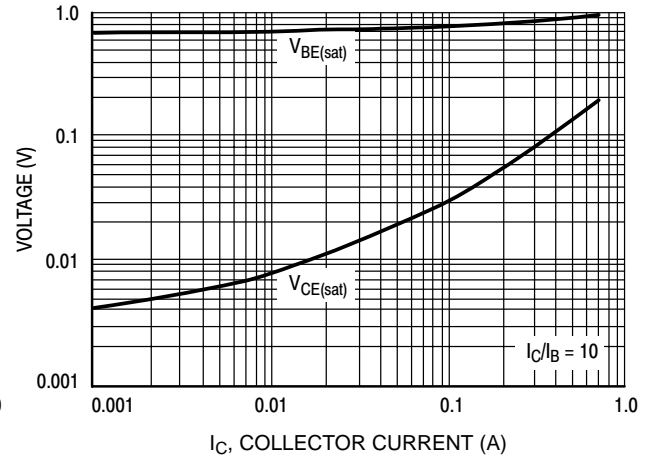


Figure 4. "ON" Voltages

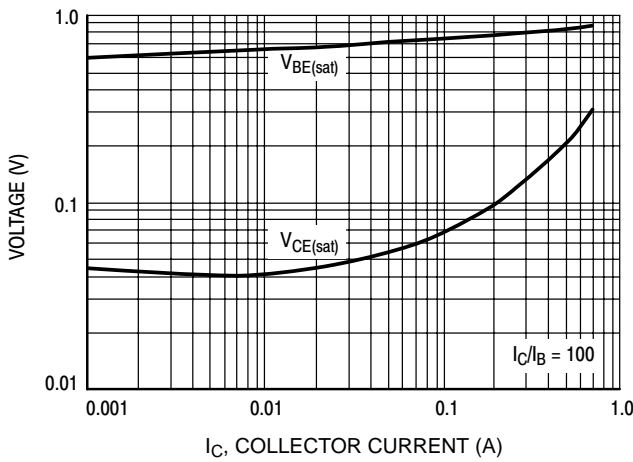


Figure 5. "ON" Voltages

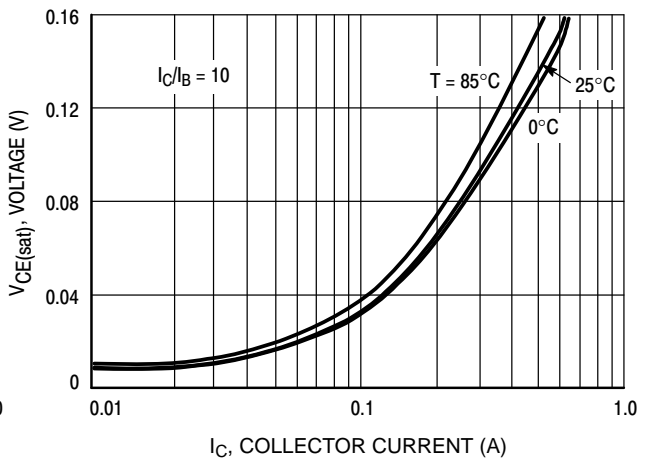


Figure 6. Collector-Emitter Saturation Voltage

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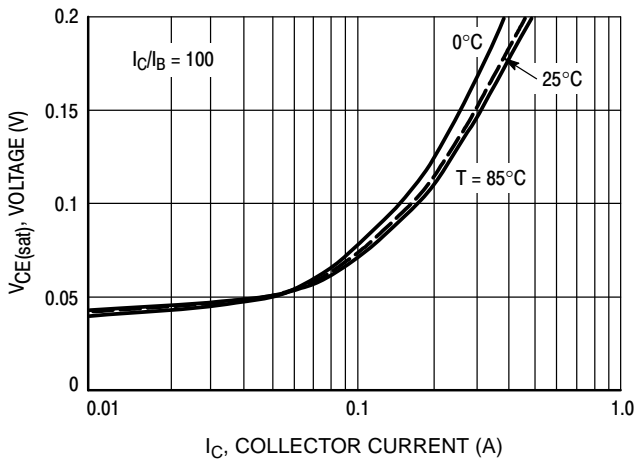


Figure 7. Collector-Emitter Saturation Voltage

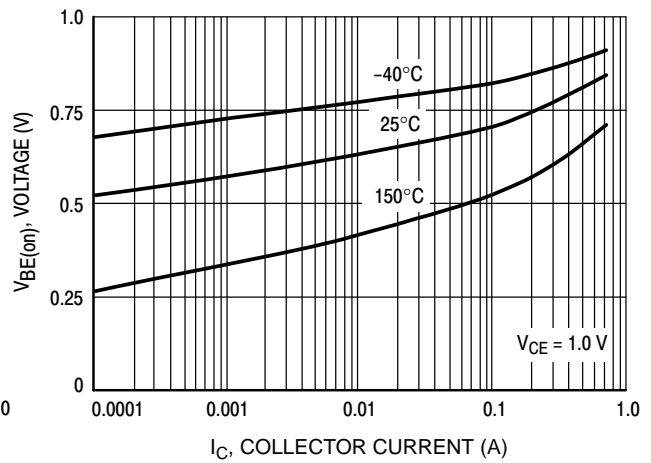


Figure 8.  $V_{BE(on)}$  Voltage

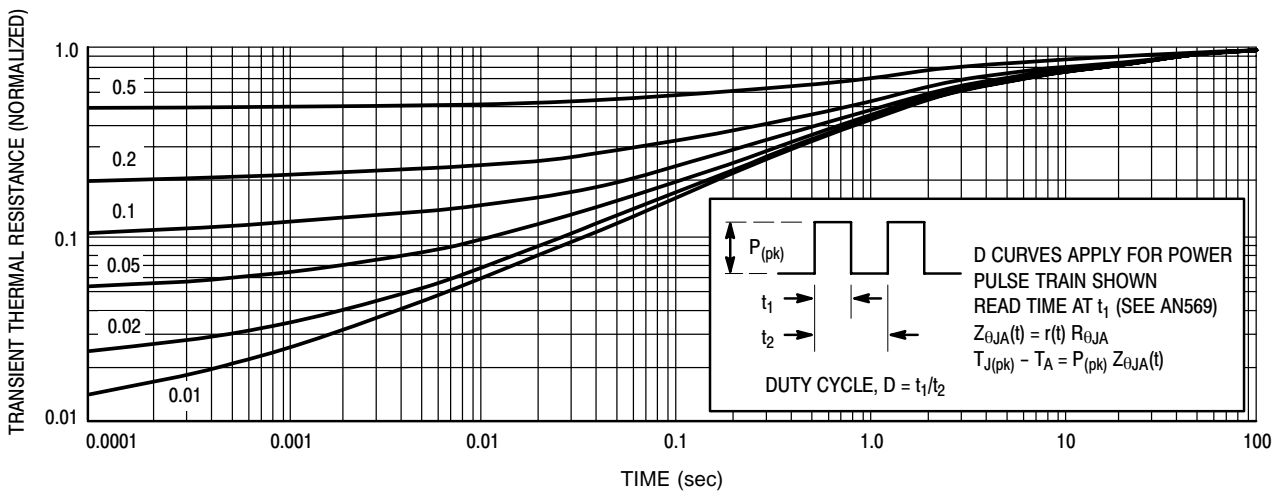
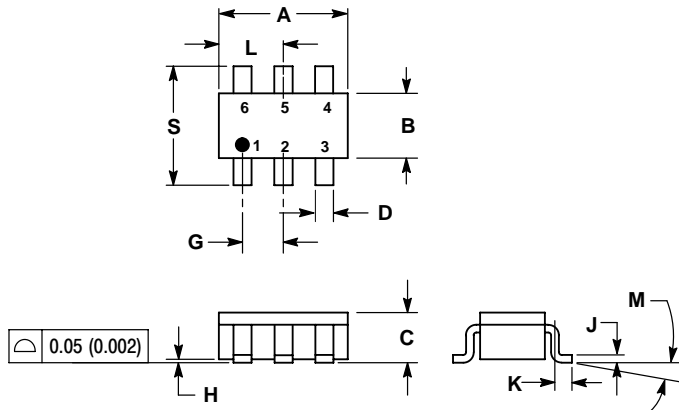


Figure 9. Thermal Response Curve

**NSS30071MR6T1G**

**PACKAGE DIMENSIONS**

**SC-74**  
CASE 318F-05  
ISSUE K



NOTES:

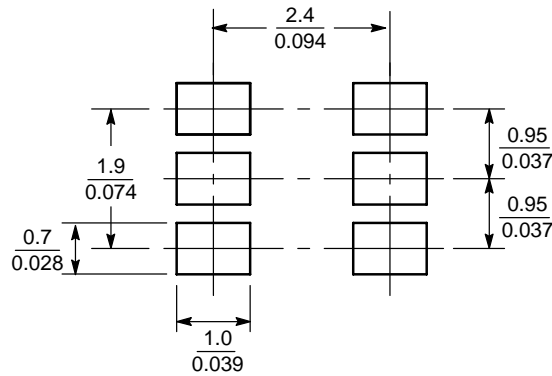
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 318F-01, -02, -03 OBSOLETE. NEW STANDARD 318F-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1142	0.1220	2.90	3.10
B	0.0512	0.0669	1.30	1.70
C	0.0354	0.0433	0.90	1.10
D	0.0098	0.0197	0.25	0.50
G	0.0335	0.0413	0.85	1.05
H	0.0005	0.0040	0.013	0.100
J	0.0040	0.0102	0.10	0.26
K	0.0079	0.0236	0.20	0.60
L	0.0493	0.0649	1.25	1.65
M	0°	10°	0°	10°
S	0.0985	0.1181	2.50	3.00

STYLE 2:


- PIN 1: NO CONNECTION
- 2: COLLECTOR
- 3: EMITTER
- 4: NO CONNECTION
- 5: COLLECTOR
- 6: BASE

**SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**NSS30071MR6T1G**

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